ASOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATIONAL AND PARTY	C. Bannockt	ourn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declarat the declaration of	ion of the su	ubstances s all lowe	within the manufactory of the materials for w	urer listed which the	item. Note: if manufacturer	the item is an as has engineering	ssembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Dist				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				rials and N	als and Mfg Information				
Supplier Information														
Company name* Com		Company un	Company unique ID			Unique ID Authority					Response Date*			
nsemi								2025-06-04						
Contact Name	tact Name Title - Contact					Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product Env			nviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repr			presentative			Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	1	Manufacturing Site		Weight*	UOM	Unit Type	
	FODM1	DM1007R2 LSOP4 TR T&I		{		2025-06-04		1	LITEONFG		117.85945	mg	Each	
Manufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Mat	al Plating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperatu		e Max Time at Peak Temperature Number of Refle		er of Reflow Cy	cles			
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	1			260 C 30		30	seconds 3					
Comments														
evel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds											
For more information regarding material of	omposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Chip	0.04429	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.0437	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0001	mg
			Supplier	Silicon (Si)	7440-21-3		0.0001	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0004	mg
Coating	4.0	mg	Supplier	Silica (SiO2)	14464-46-1		4	mg
Die Attach	0.26	mg	Supplier	Silver (Ag)	7440-22-4		0.2	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.02	mg
			Supplier	Dicyandiamine	461-58-5		0.01	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.02	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.01	mg
Lead Frame	1.808	mg	Supplier	Silver (Ag)	7440-22-4		0.268	mg
			Supplier	Copper (Cu)	7440-50-8		1.54	mg
Mold Compound-Black	74.042	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		9.662	mg
			Supplier	Carbon Black (C)	1333-86-4		0.74	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.66	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		5.18	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		51.8	mg
Mold Compound-White	35.0025	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		7.0005	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		24.5017	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.5002	mg
lating	2.5	mg	Supplier	Tin (Sn)	7440-31-5		2.5	mg
PTR Die	0.13266	mg	Supplier	Boron (B)	7440-42-8		0.0007	mg
			Supplier	Silicon (Si)	7440-21-3		0.13	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0007	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0013	mg
Wire Bond - Au	0.07	mg	Supplier	Gold (Au)	7440-57-5		0.07	mg